



US00D387364S

United States Patent [19]

Boucher et al.

[11] Patent Number: **Des. 387,364**

[45] Date of Patent: ****Dec. 9, 1997**

[54] SEMICONDUCTOR WAFER DICING SAW

[76] Inventors: **John N. Boucher**, 110 Coveridge La., Longwood, Fla. 32779; **David E. Bajune**, 6800 W. S.R. 46, Sanford, Fla. 32773

[**] Term: **14 Years**

[21] Appl. No.: **56,194**

[22] Filed: **Jun. 25, 1996**

[51] LOC (6) Cl. **15-09**

[52] U.S. Cl. **D15/133; D15/127**

[58] Field of Search **D15/127, 133; 83/404; 125/13.01, 35; 437/226, 227; 451/6, 21**

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 274,817	7/1984	Jenkins	D15/127 X
4,059,927	11/1977	Robillard	451/21 X
4,407,262	10/1983	Wirz et al.	125/13.01

Primary Examiner—Antoine Duval Davis
Attorney, Agent, or Firm—Allen, Dyer, Doppelt, Milbrath & Gilchrist, P.A.

[57] **CLAIM**

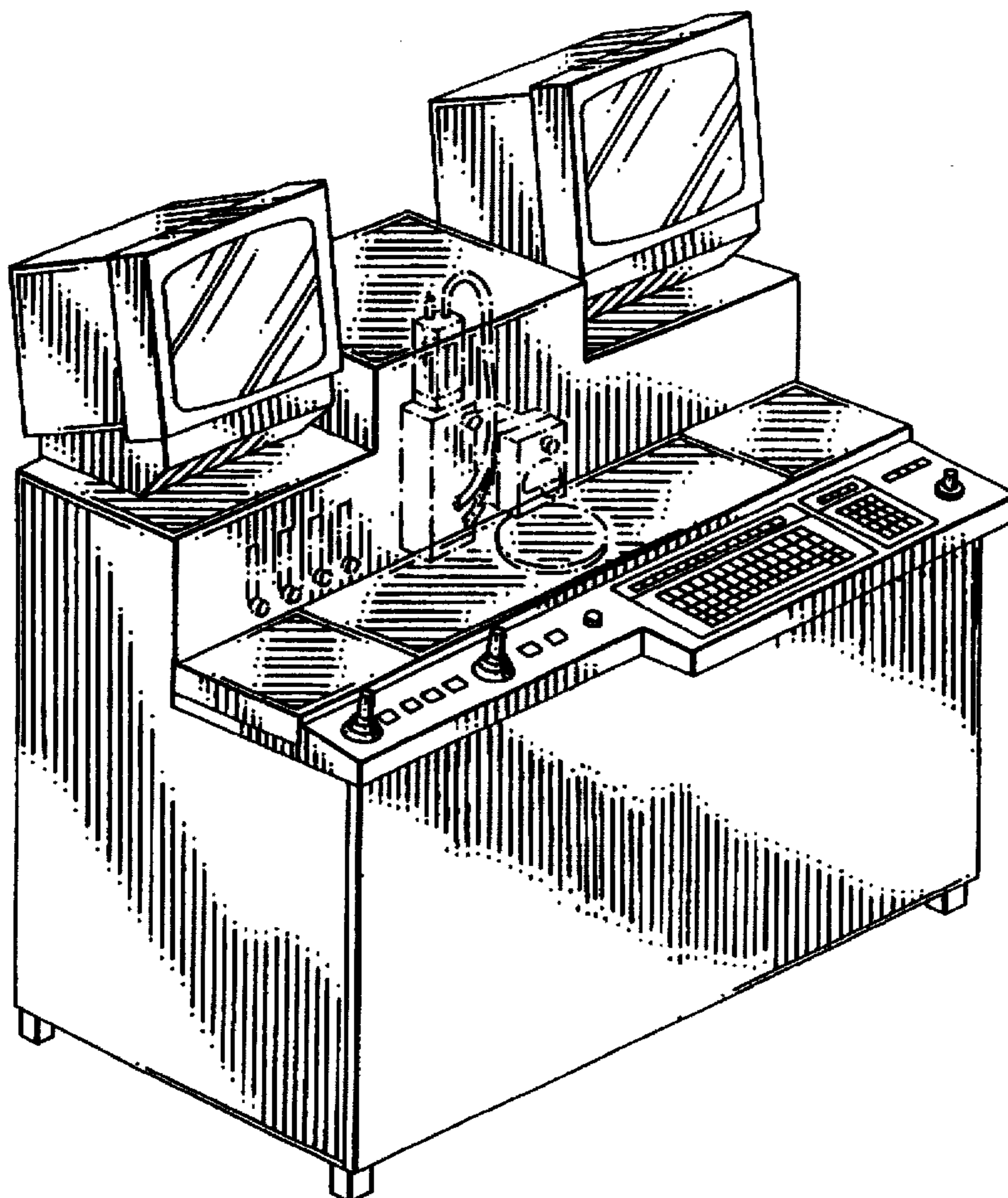
The ornamental design for a semiconductor wafer dicing saw, as shown and described.

DESCRIPTION

FIG. 1 is a top, left front perspective view of a semiconductor wafer dicing saw showing our new design; FIG. 2 is a right side elevational view thereof; FIG. 3 is a left side elevational view thereof; FIG. 4 is a top plan view thereof; FIG. 5 is a bottom plan view thereof; FIG. 6 is a rear elevational view thereof; FIG. 7 is a top, left perspective view of a second embodiment of FIG. 1, the difference being inclusion of coolant controls, camera, blade housing and chuck; FIG. 8 is a right side elevational view of FIG. 7; FIG. 9 is a left side elevational view of FIG. 7; FIG. 10 is a top plan view of FIG. 7; FIG. 11 is a bottom plan view of FIG. 7; and, FIG. 12 is a rear elevational view of FIG. 7.

The broken line showing of keyboard keys, coolant controls, camera, blade housing and chuck in FIGS. 1-4 and 6 is for illustrative purposes only and forms no part on the claimed design for the embodiment of FIGS. 1-6.

1 Claim, 3 Drawing Sheets



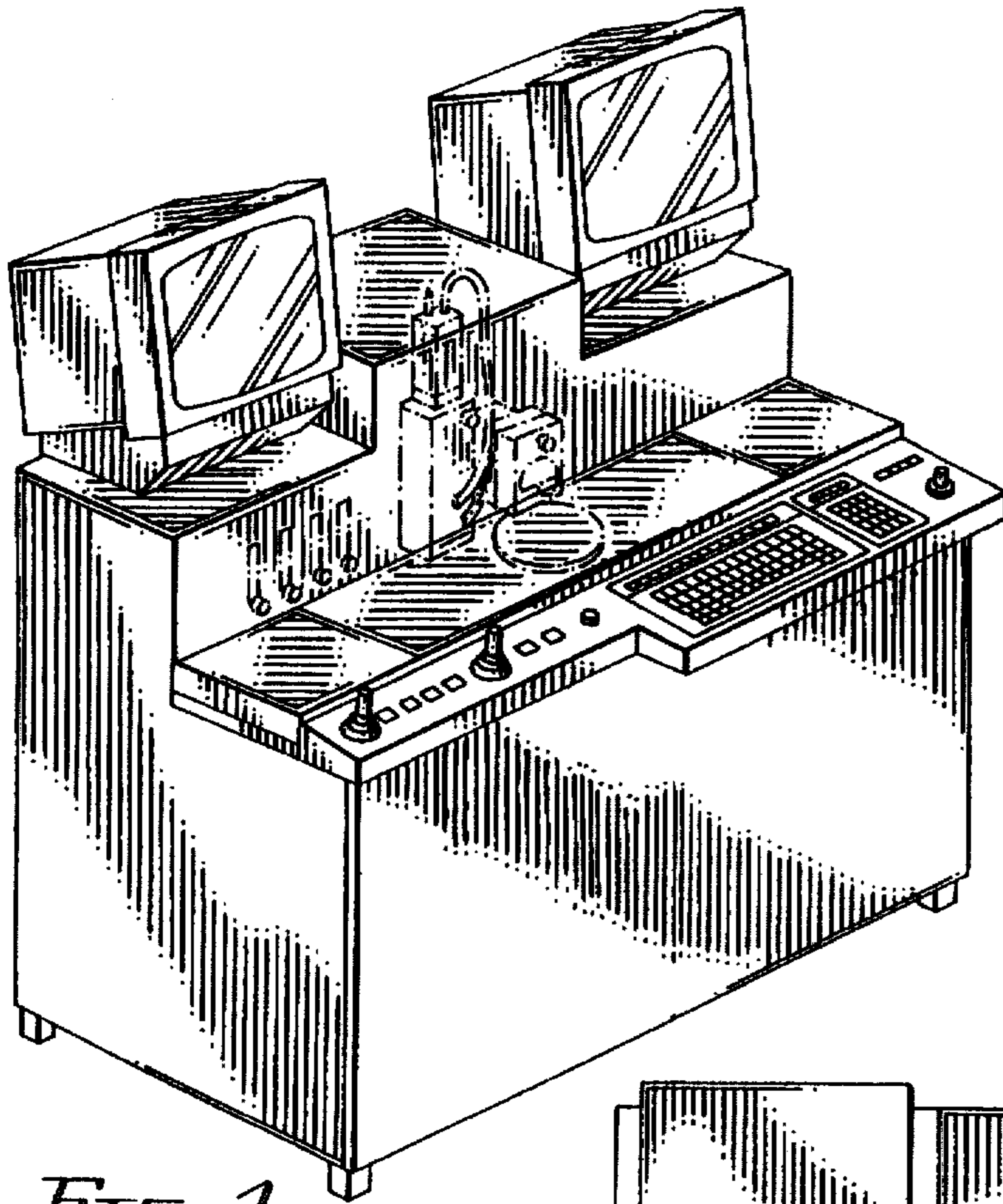


FIG 1

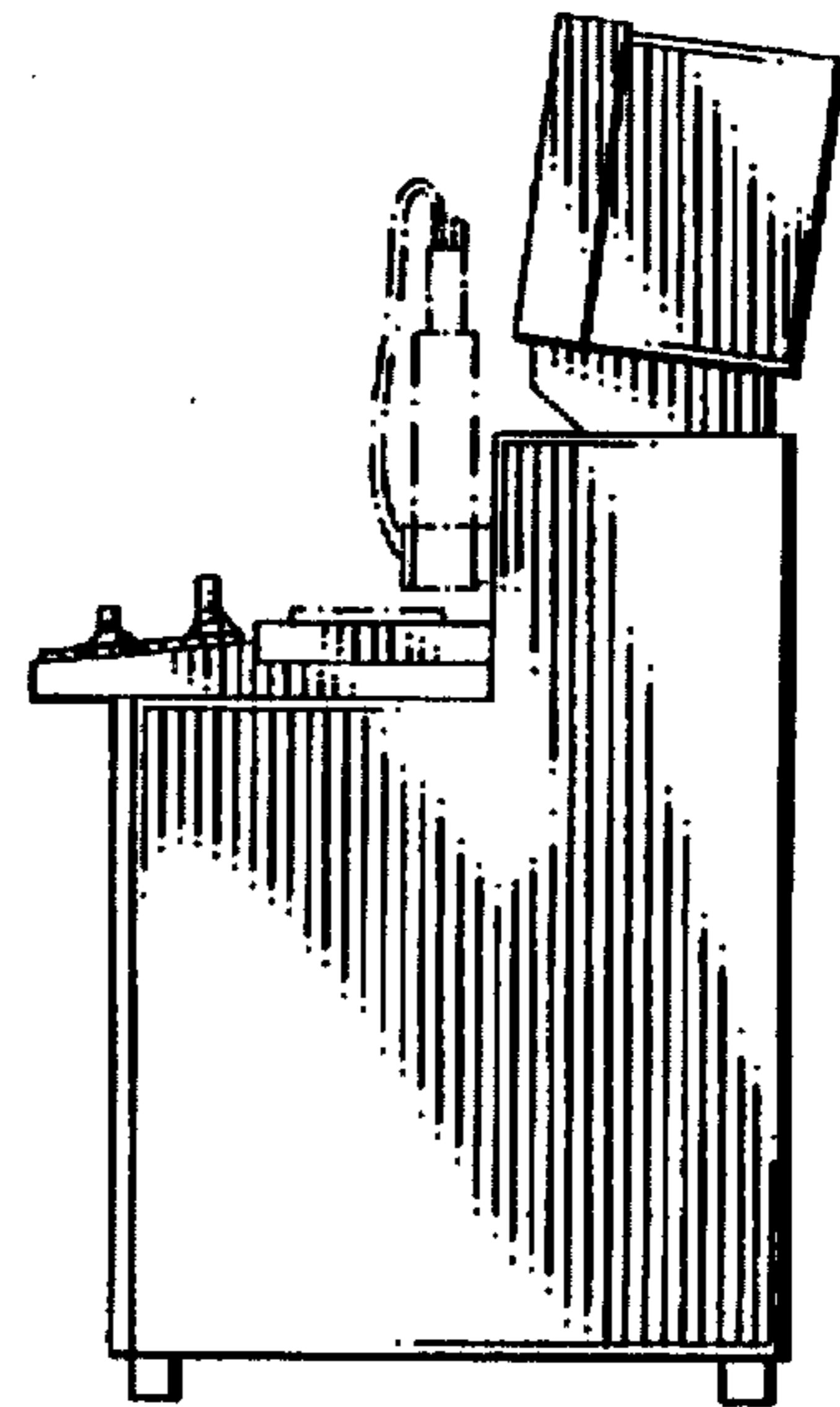


FIG 2

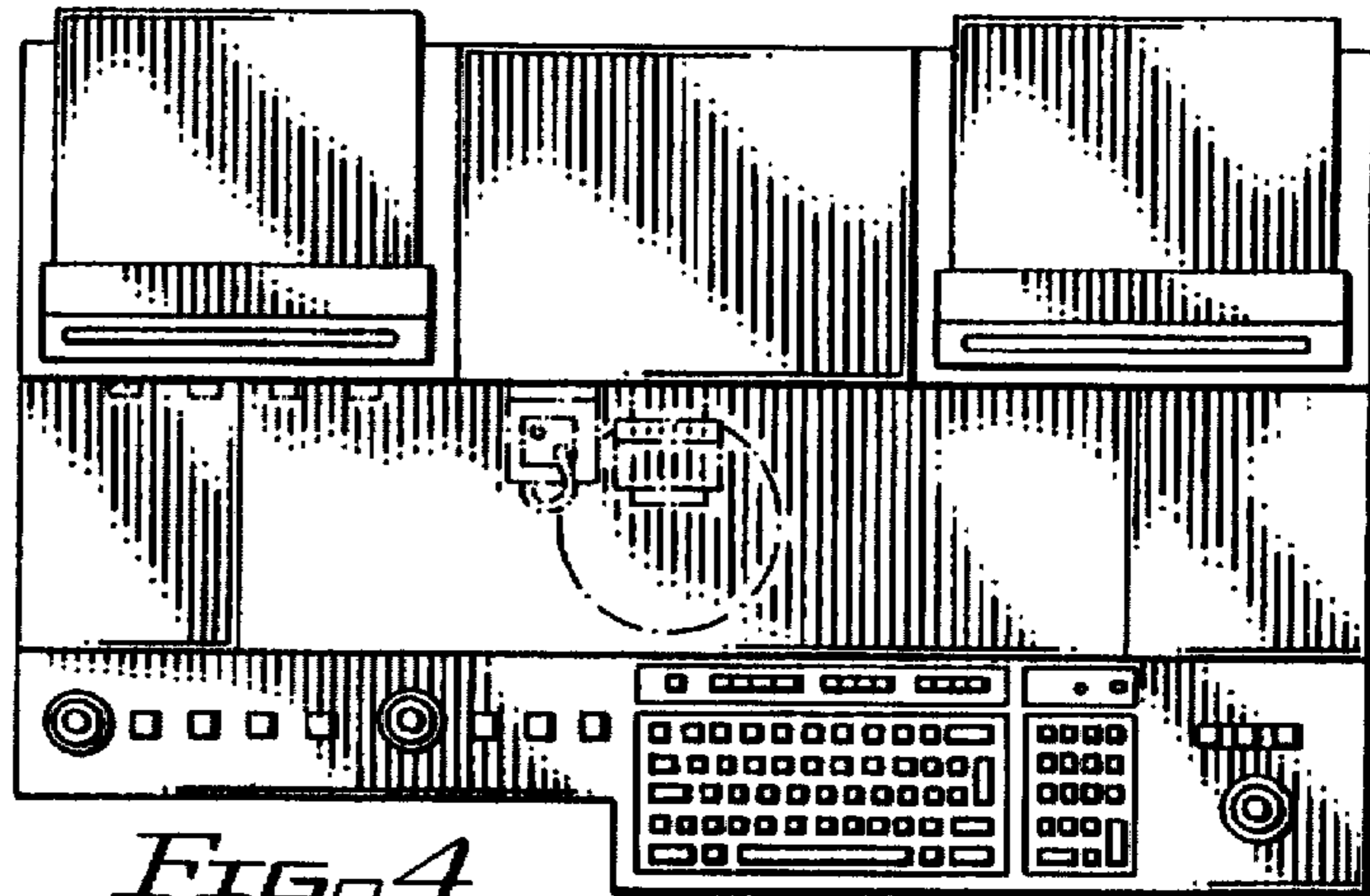


FIG 4

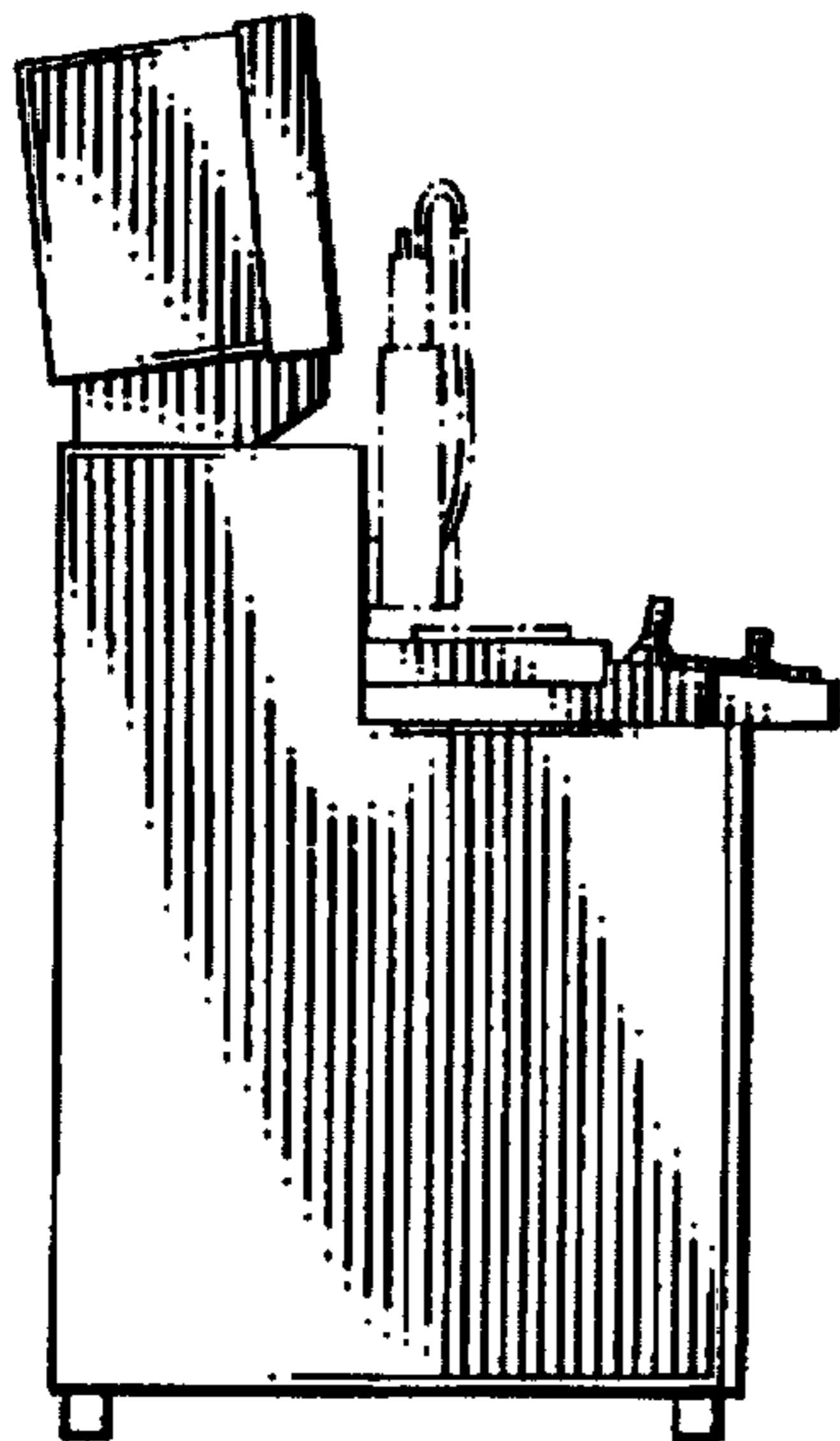


FIG 3

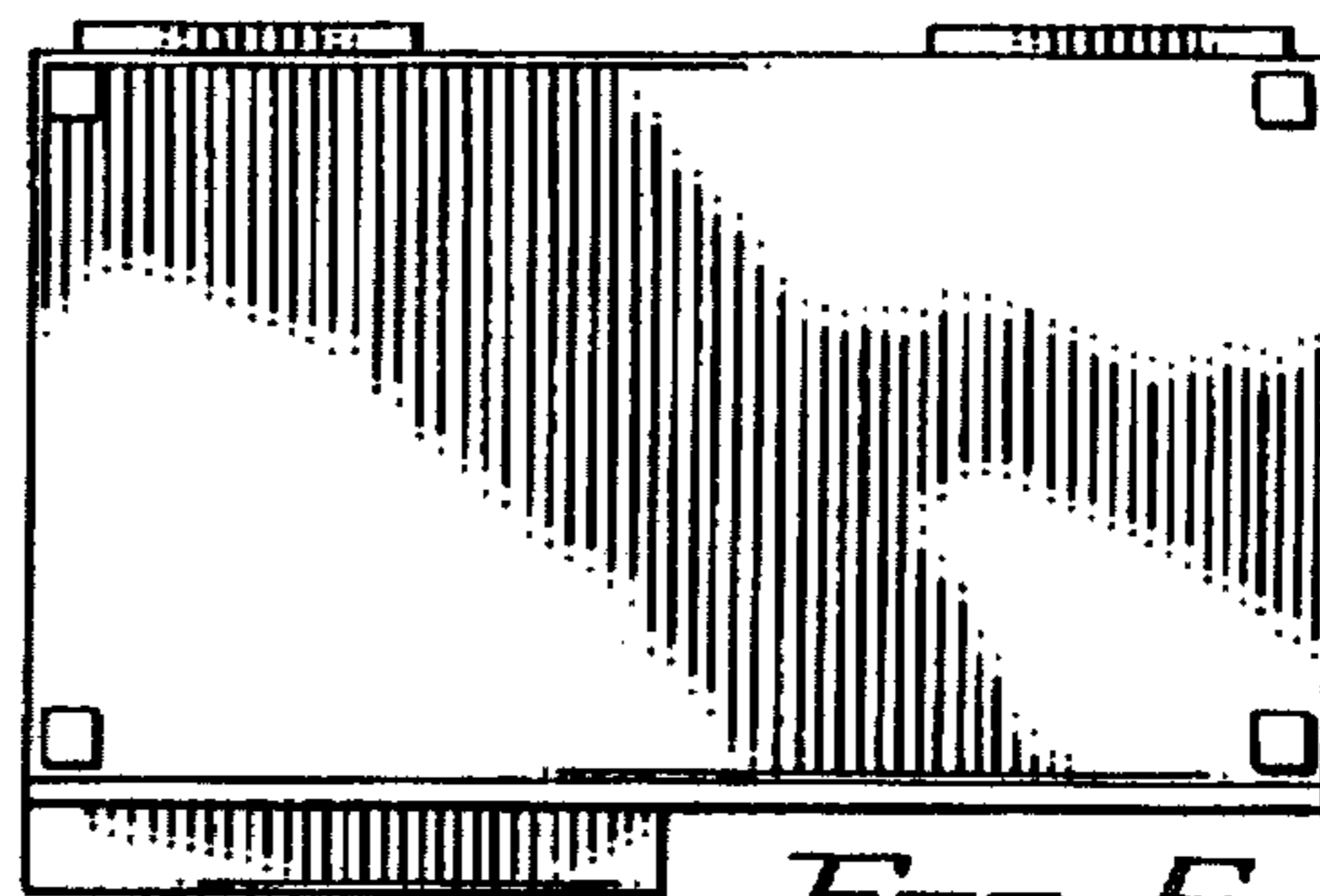


FIG 5

FIG. 7

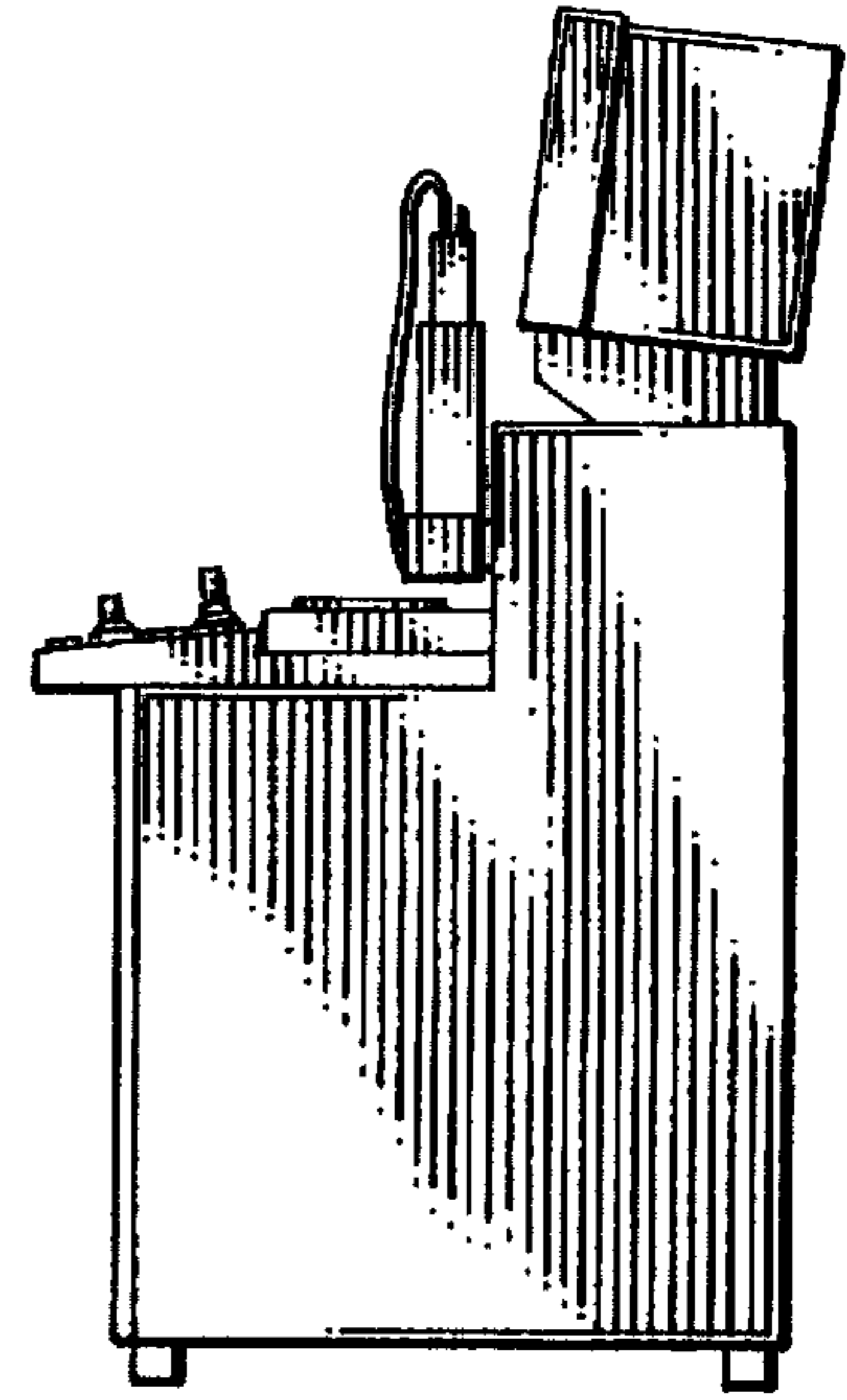
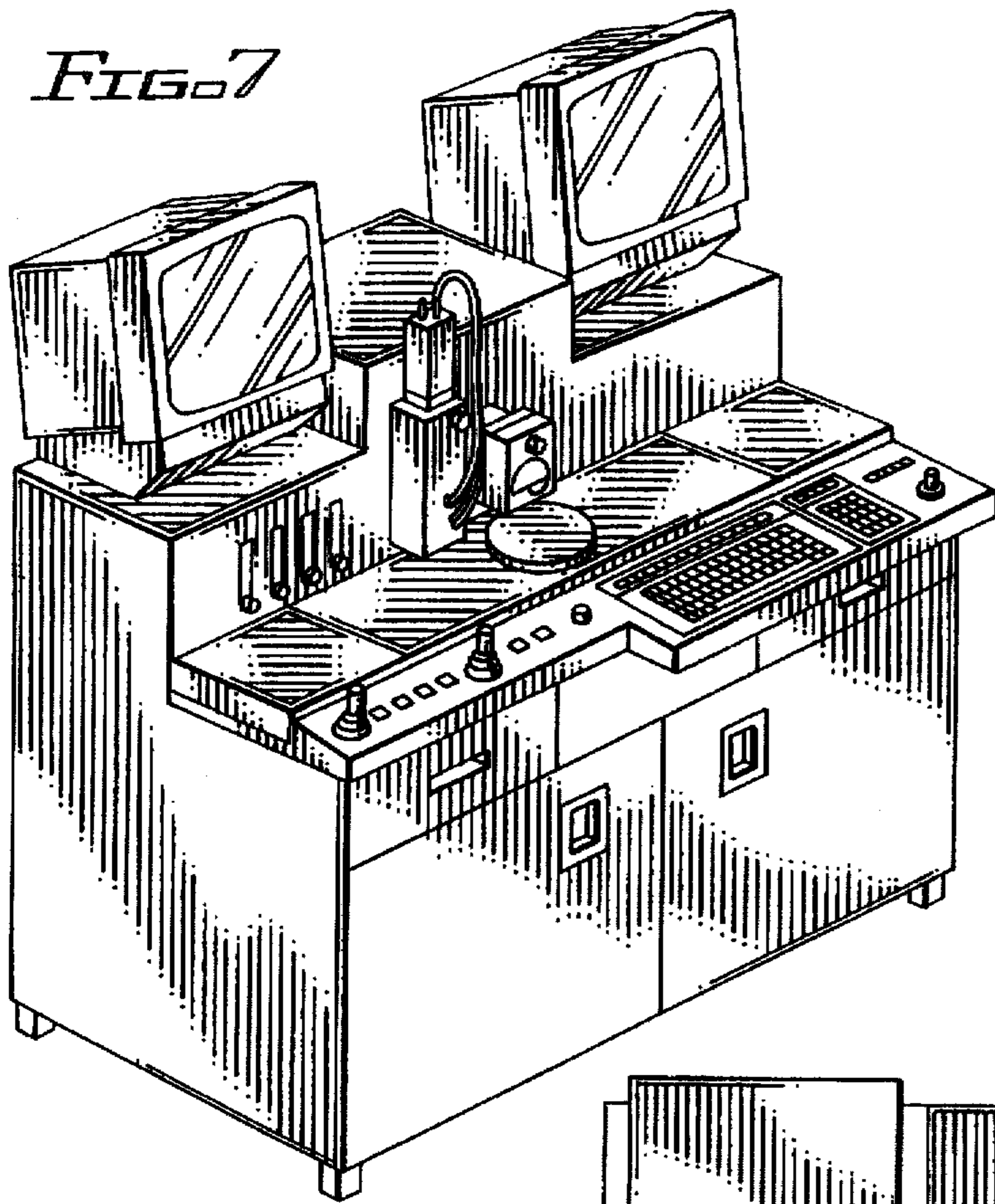


FIG. 8

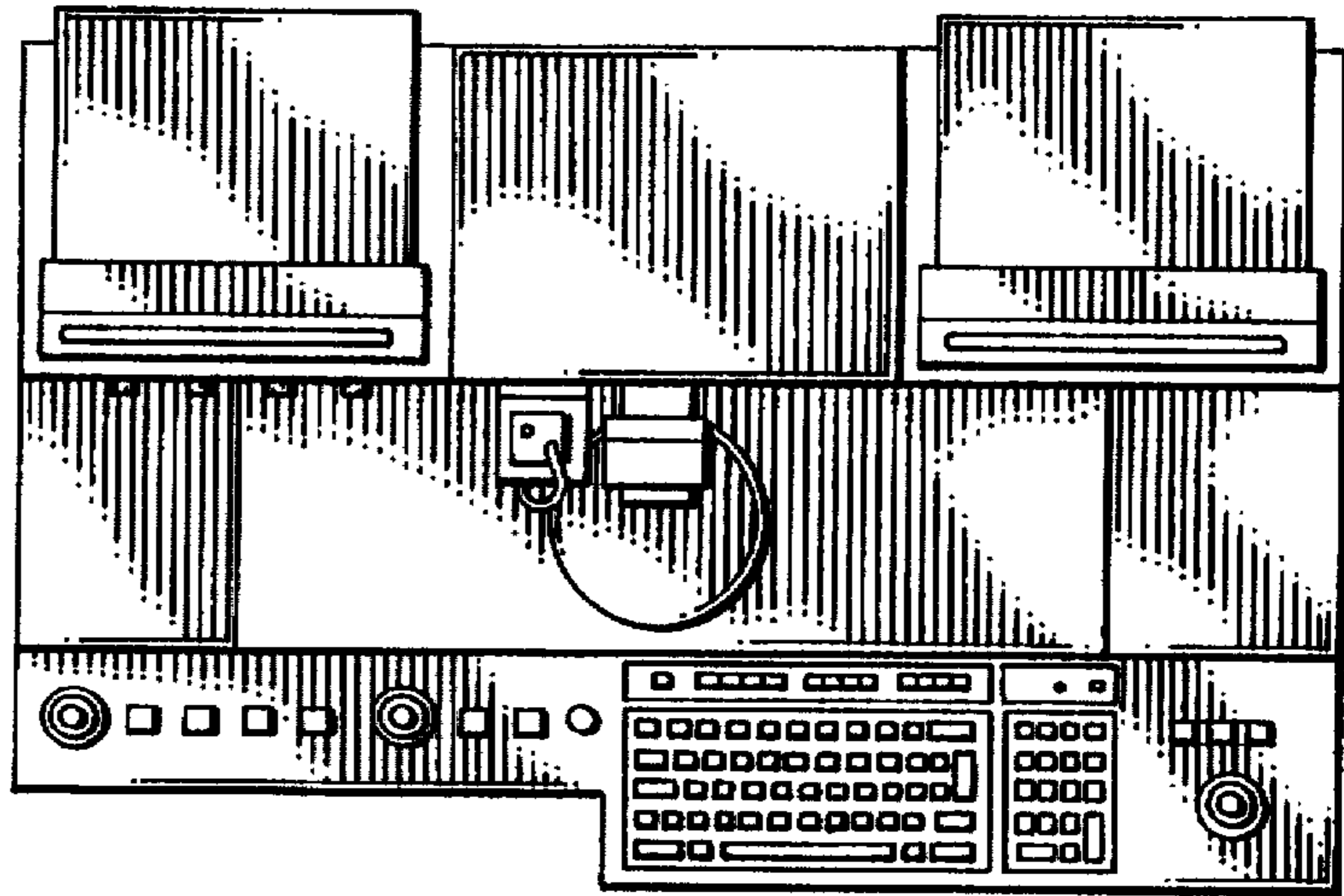


FIG. 10

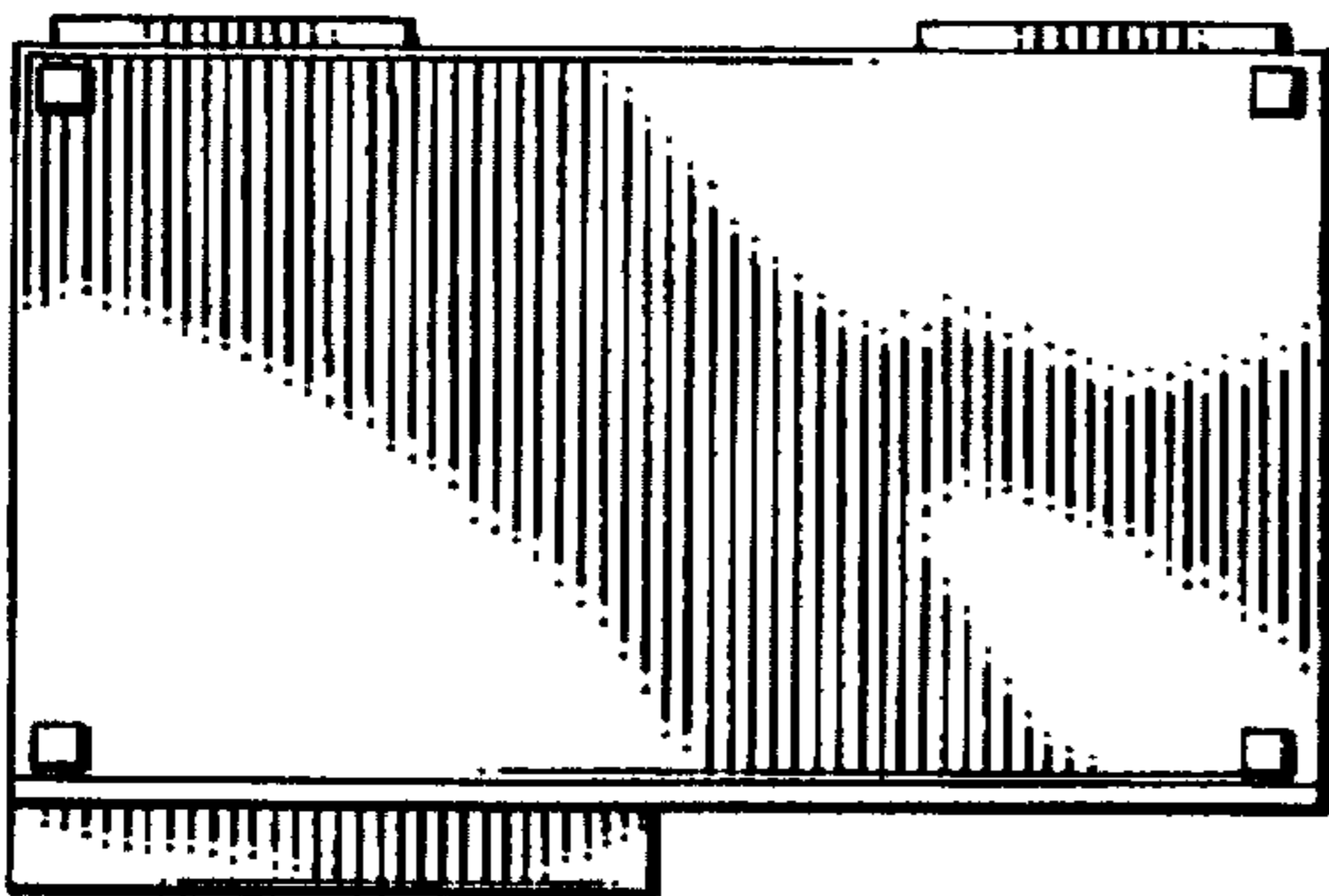


FIG. 11

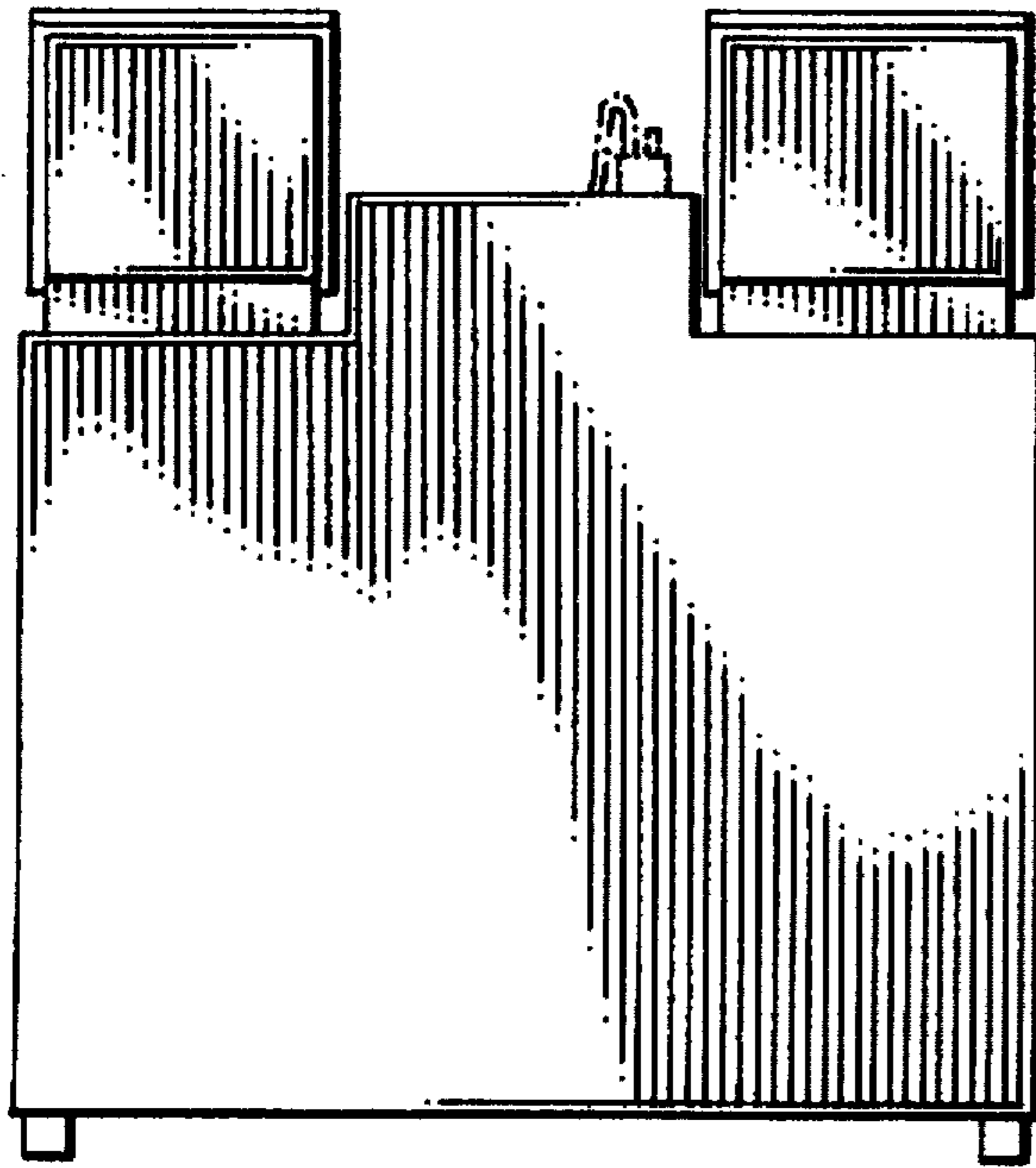


FIG. 6

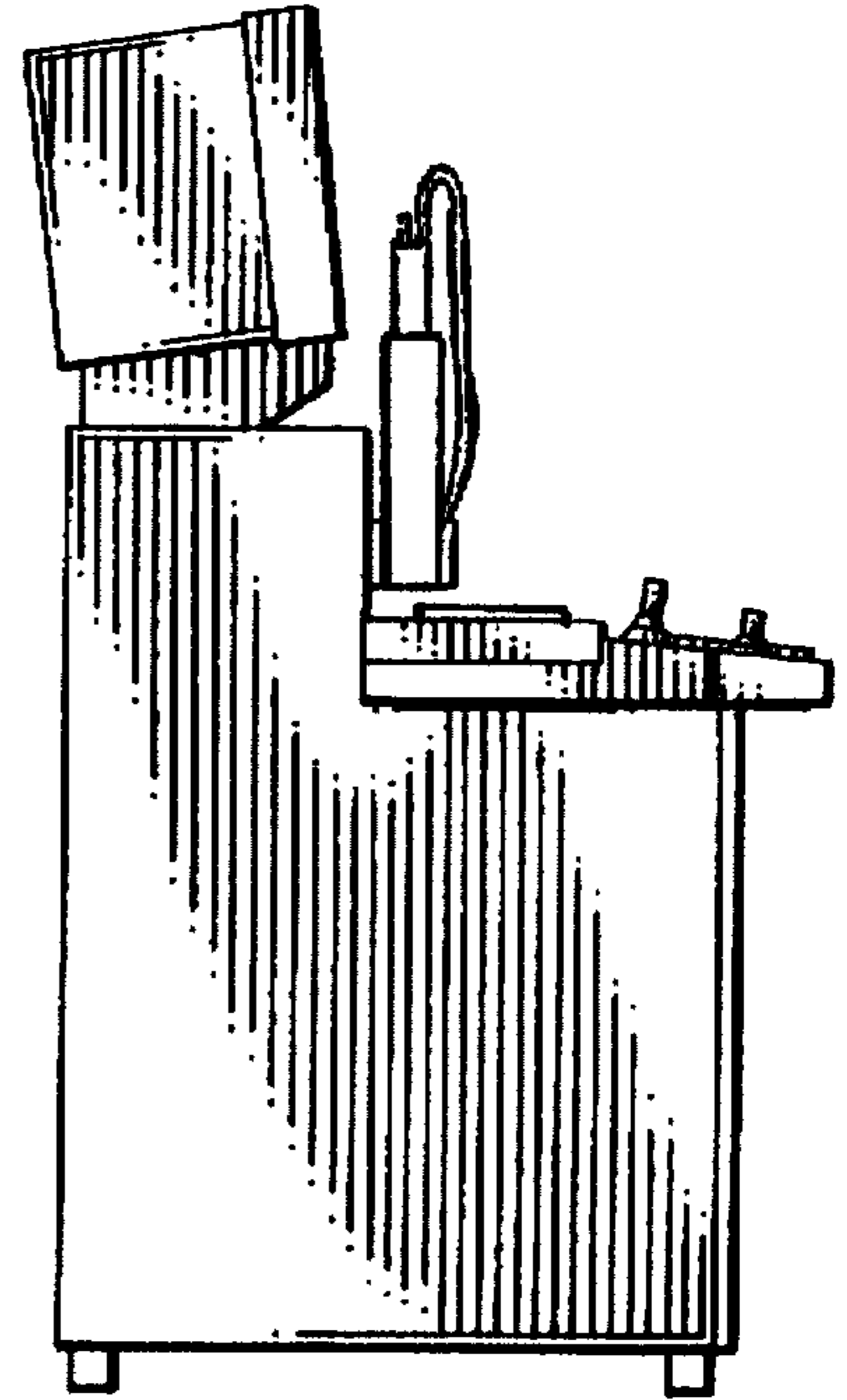


FIG. 9

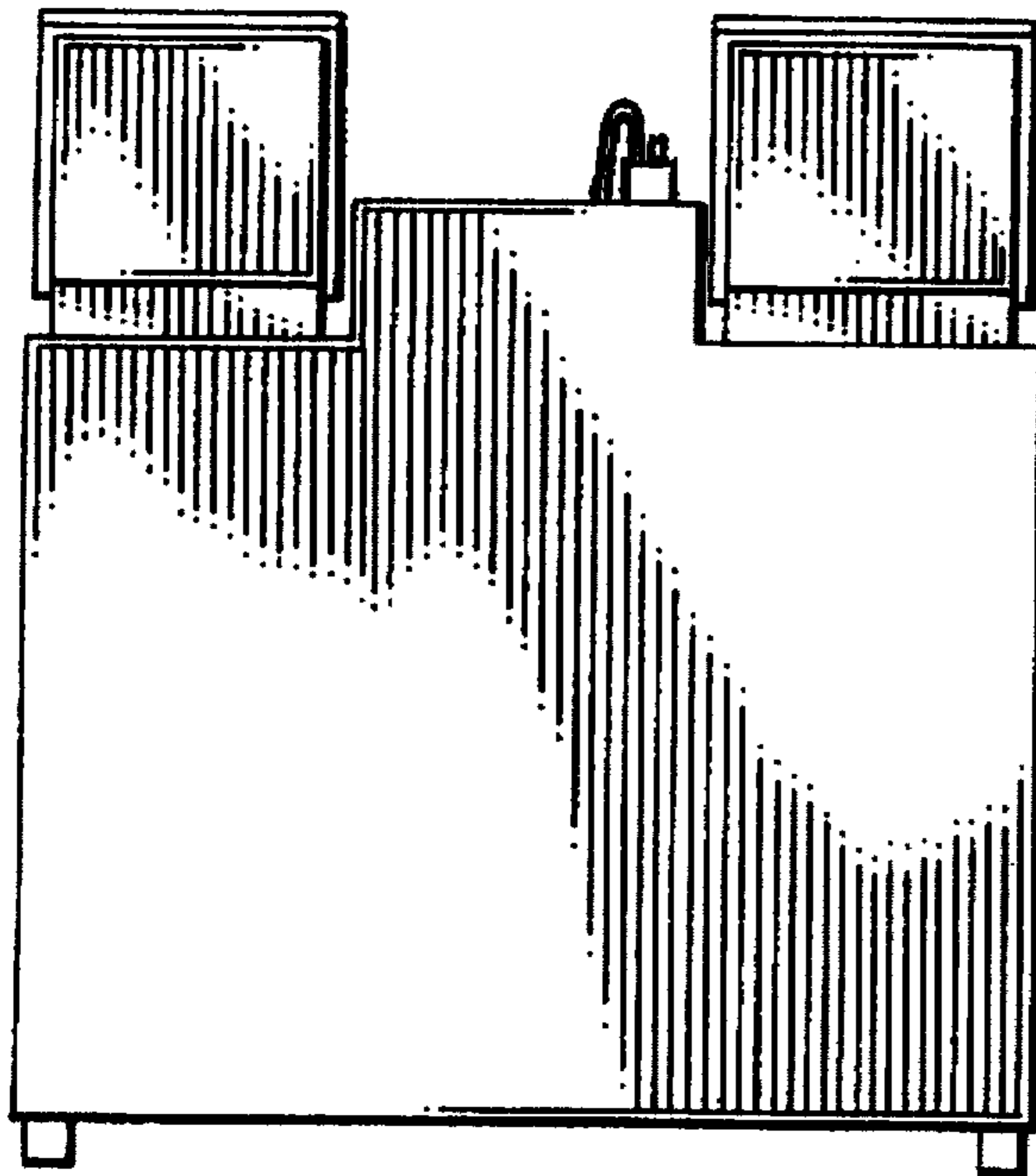


FIG. 12